

# GSM1913

## 20V P-Channel Enhancement Mode MOSFET

### Product Description

GSM1913, P-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent  $R_{DS(ON)}$ , low gate charge.

These devices are particularly suited for low Voltage power management, such as smart phone and notebook computer, and low in-line power loss are needed in commercial industrial surface mount applications.

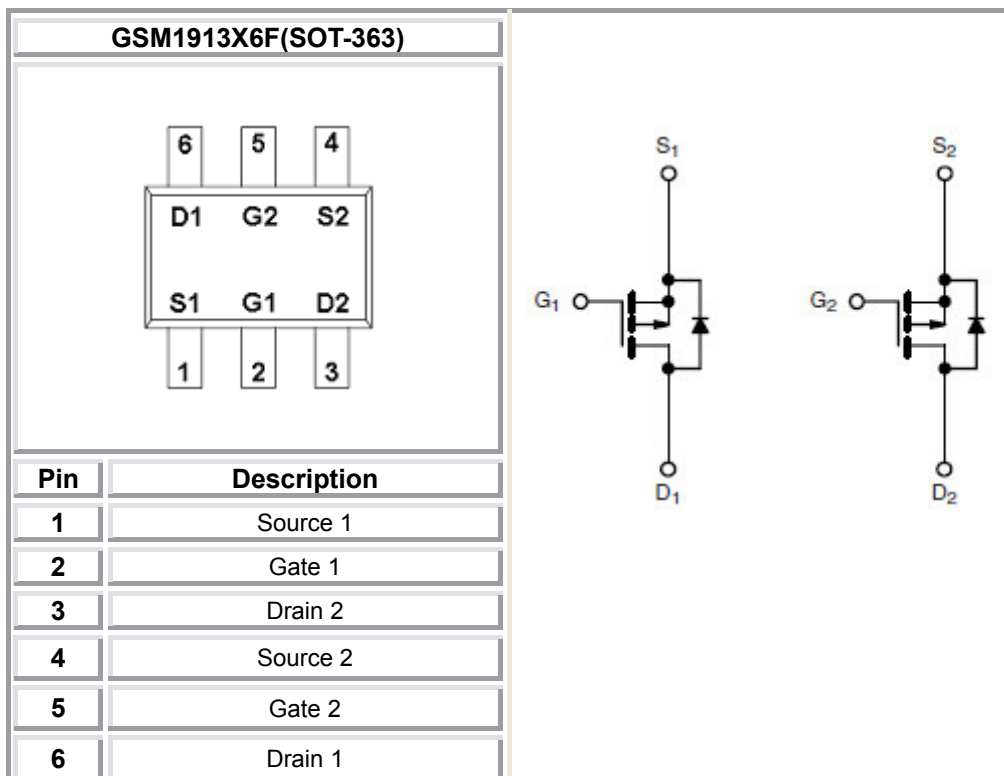
### Features

- -20V/-0.6A,  $R_{DS(ON)}=600m\Omega@V_{GS}=-4.5V$
- -20V/-0.5A,  $R_{DS(ON)}=800m\Omega@V_{GS}=-2.5V$
- -20V/-0.4A,  $R_{DS(ON)}=1600m\Omega@V_{GS}=-1.8V$
- Low Offset (Error) Voltage
- Low-Voltage Operation
- High-Speed Circuits
- Low Battery Voltage Operation
- SOT-363 package design

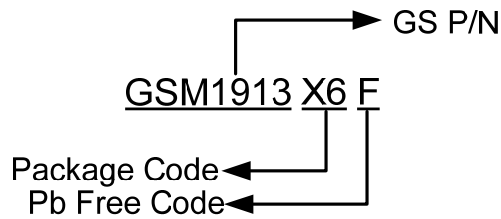
### Applications

- Drivers: Relays, Solenoids, Lamps, Hammers, Displays, Memories
- Battery Operated Systems
- Load/Power Switching Smart Phones, Pagers
- PA Switch
- Level Switch

### Packages & Pin Assignments

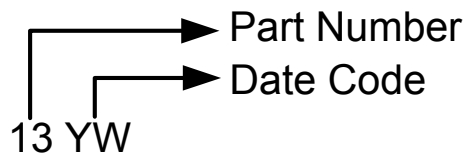


## Ordering Information



Part Number	Package	Quantity Reel
GSM1913X6F	SOT-363	3000 PCS

## Marking Information



## Absolute Maximum Ratings

( $T_A=25^\circ\text{C}$  unless otherwise noted)

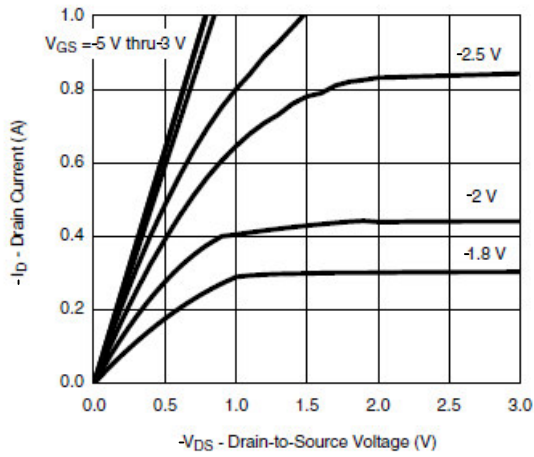
Symbol	Parameter	Typical	Unit	
$V_{DS}$	Drain-Source Voltage	-20	V	
$V_{GS}$	Gate -Source Voltage	$\pm 12$	V	
$I_D$	Continuous Drain Current( $T_J=150^\circ\text{C}$ )	$T_A=25^\circ\text{C}$	-1.4	A
		$T_A=70^\circ\text{C}$	-1.0	
$I_{DM}$	Pulsed Drain Current	-6	A	
$I_S$	Continuous Source Current(Diode Conduction)	-1	A	
$P_D$	Power Dissipation	$T_A=25^\circ\text{C}$	0.3	W
		$T_A=70^\circ\text{C}$	0.2	
$T_J$	Operating Junction Temperature	-55/150	$^\circ\text{C}$	
$T_{STG}$	Storage Temperature Range	-55/150	$^\circ\text{C}$	

## Electrical Characteristics

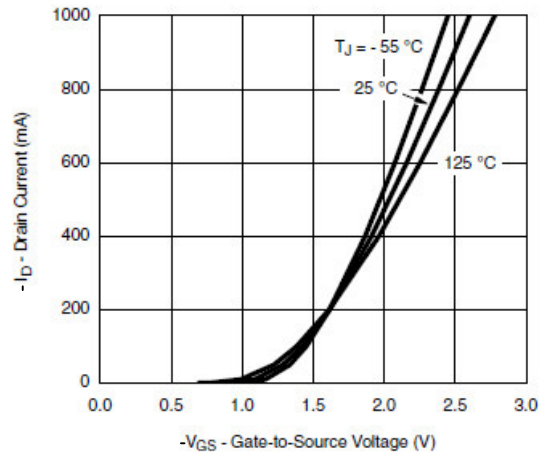
(T<sub>A</sub>=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =-250uA	-20			V
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250uA	-0.4		-1.0	
I <sub>GSS</sub>	Gate Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±12V			±100	nA
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =-20V, V <sub>GS</sub> =0V			-1	uA
		V <sub>DS</sub> =-20V, V <sub>GS</sub> =0V T <sub>J</sub> =85°C			-5	
I <sub>D(on)</sub>	On-State Drain Current	V <sub>DS</sub> ≤ -5V, V <sub>GS</sub> =-4.5V	-0.7			A
R <sub>DS(on)</sub>	Drain-Source On-Resistance	V <sub>GS</sub> = -4.5V, I <sub>D</sub> =-0.6A		460	600	mΩ
		V <sub>GS</sub> = -2.5V, I <sub>D</sub> =-0.5A		680	800	
		V <sub>GS</sub> = -1.8V, I <sub>D</sub> =-0.4A		1200	1600	
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =-10V, I <sub>D</sub> =-0.4A		1		S
V <sub>SD</sub>	Diode Forward Voltage	I <sub>S</sub> =-0.15A, V <sub>GS</sub> =0V		-0.65	-1.2	V
<b>Dynamic</b>						
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =-10V, V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-0.25A		1.0	1.3	nC
Q <sub>gs</sub>	Gate-Source Charge			0.1		
Q <sub>gd</sub>	Gate-Drain Charge			0.3		
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =-10V, V <sub>GS</sub> =0V, f=1MHz		70	100	pF
C <sub>oss</sub>	Output Capacitance			20		
C <sub>rss</sub>	Reverse Transfer Capacitance			10		
t <sub>d(on)</sub>	Turn-On Time	V <sub>DD</sub> =-10V, R <sub>L</sub> =30Ω, I <sub>D</sub> =-0.2A, V <sub>GEN</sub> =-4.5V, R <sub>G</sub> =10Ω		10	15	ns
t <sub>r</sub>				10	15	
t <sub>d(off)</sub>	Turn-Off Time			40	60	
t <sub>f</sub>				30	50	

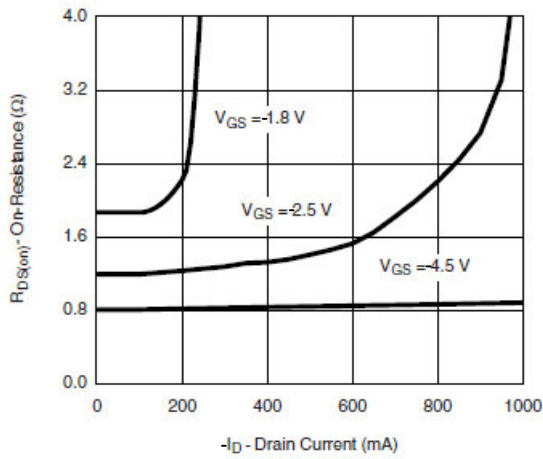
## Typical Performance Characteristics



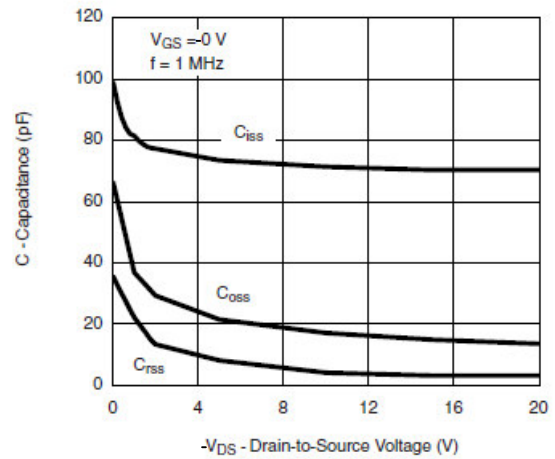
Output Characteristics



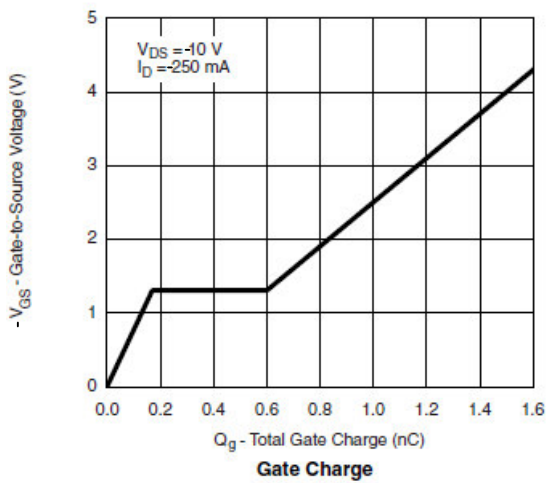
Transfer Characteristics



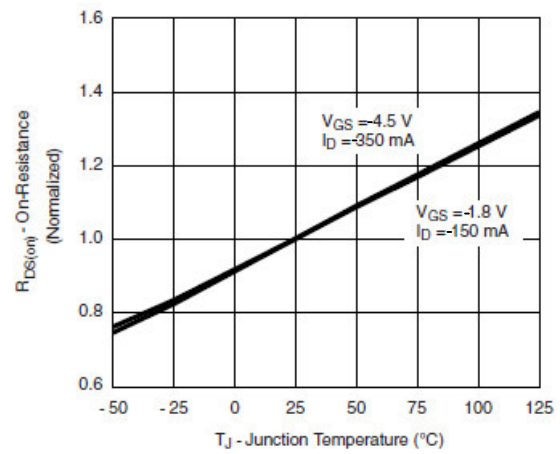
On-Resistance vs. Drain Current



Capacitance

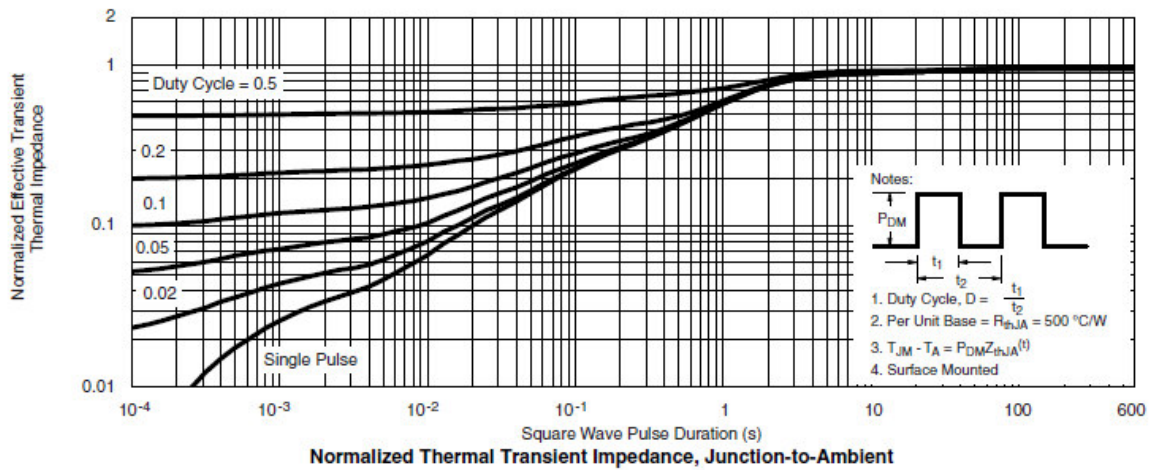
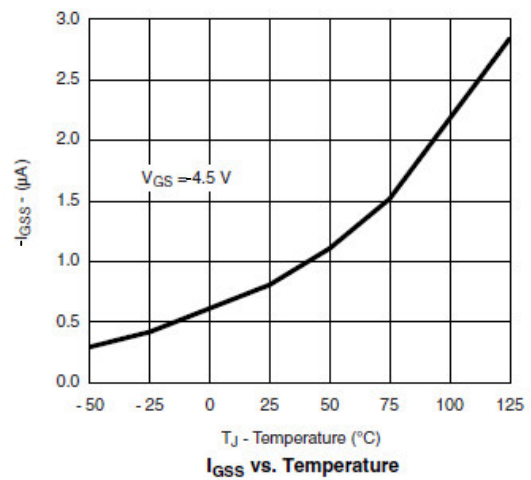
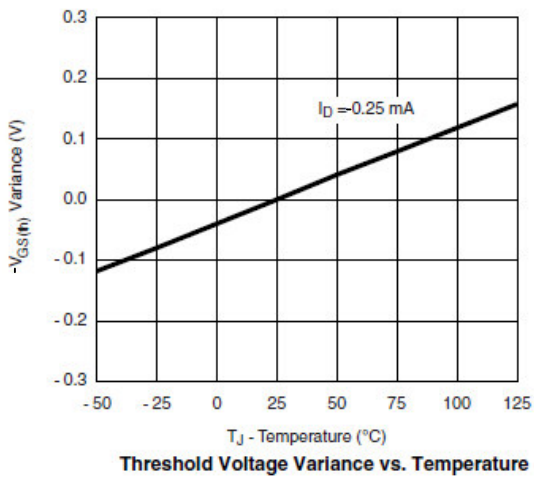
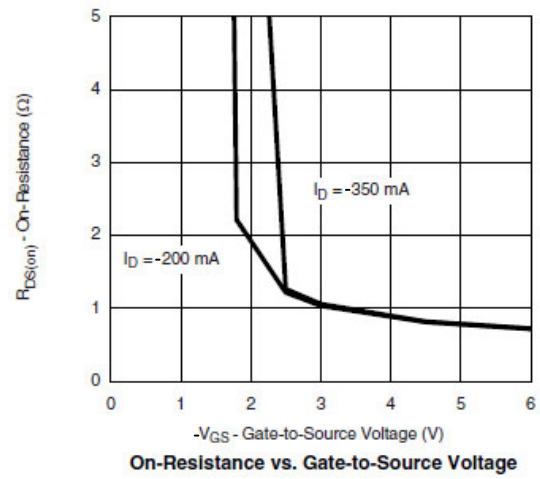
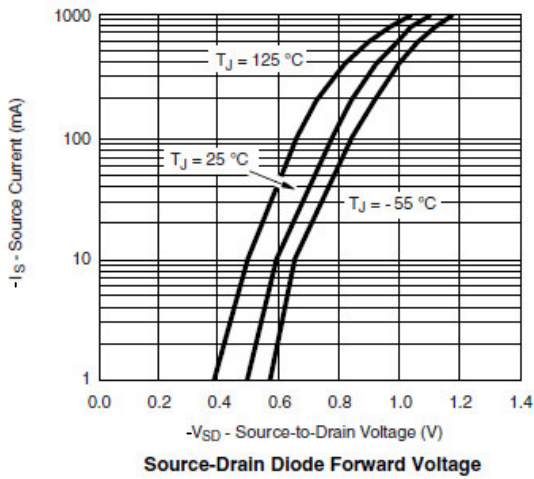


Gate Charge



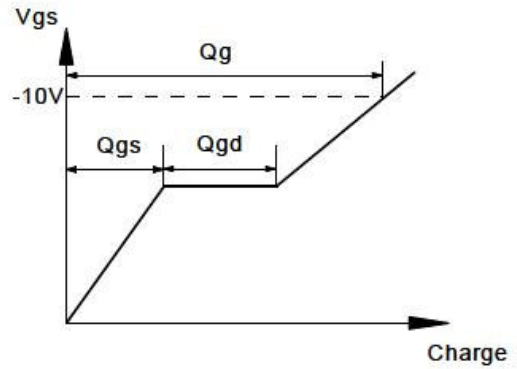
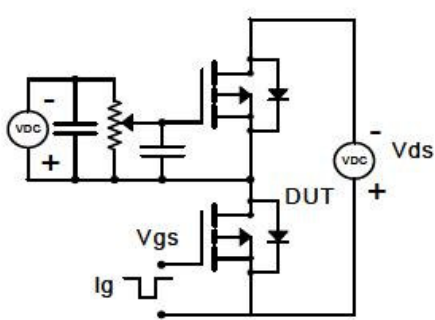
On-Resistance vs. Junction Temperature

## Typical Performance Characteristics (continue)

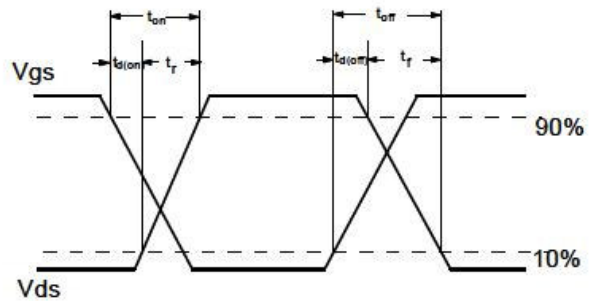
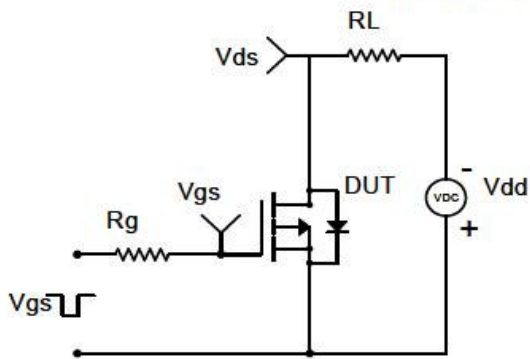


## Typical Performance Characteristics (continue)

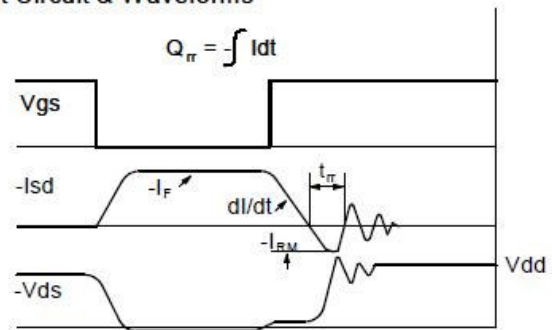
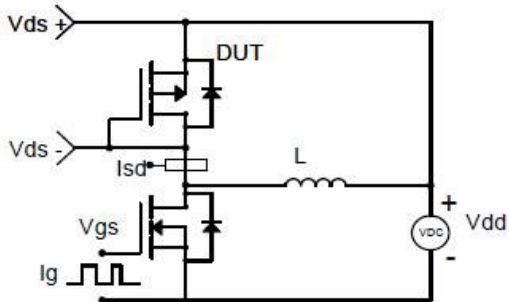
### Gate Charge Test Circuit & Waveform



### Resistive Switching Test Circuit & Waveforms

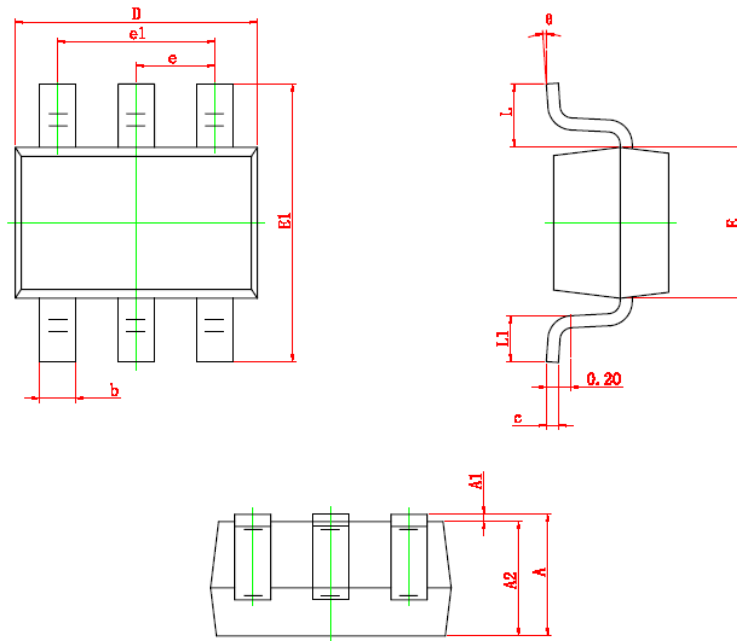


### Diode Recovery Test Circuit & Waveforms



## Package Dimension

### SOT-363







Dimensions				
SYMBOL	Millimeters		Inches	
	MIN	MAX	MIN	MAX
A	0.90	1.10	0.035	0.043
A1	0.00	0.10	0.000	0.004
A2	0.90	1.00	0.035	0.039
b	0.15	0.35	0.006	0.014
c	0.08	0.15	0.003	0.006
D	2.00	2.20	0.079	0.087
E	1.15	1.35	0.045	0.053
E1	2.15	2.45	0.085	0.096
e	0.650 (TYP)		0.026 (TYP)	
e1	1.20	1.40	0.047	0.055
L	0.525 REF		0.021 REF	
L1	0.26	0.46	0.01	0.018
θ	0°	8°	0°	8°





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